

Bonding method

Abstract

The invention relates to a method for bonding a first surface (1a) and a second surface (7a) by means of an interlayer (3), comprising the steps:

- 5 a) providing a first item (1) which has the first surface (1a),
- b) providing flowable, solidifiable material for the interlayer (3),
- c) providing a second item (7) which has the second surface (7a),
- d) applying the material for the interlayer onto the first surface (1a) so that a bulge (3a) encircling the surface is produced,
- 10 e) applying a vacuum around the first item (1) and the second item (2),
- f) bringing the second surface (7a) of the second item (7) into contact with the circumferential bulge so that a sealed-off cavity (5) is produced,
- g) increasing the ambient pressure so that the cavity (5) is eliminated without resulting in a stream of gas flowing into the cavity and
- 15 h) increasing the viscosity of the material for the interlayer.

Fig. 1